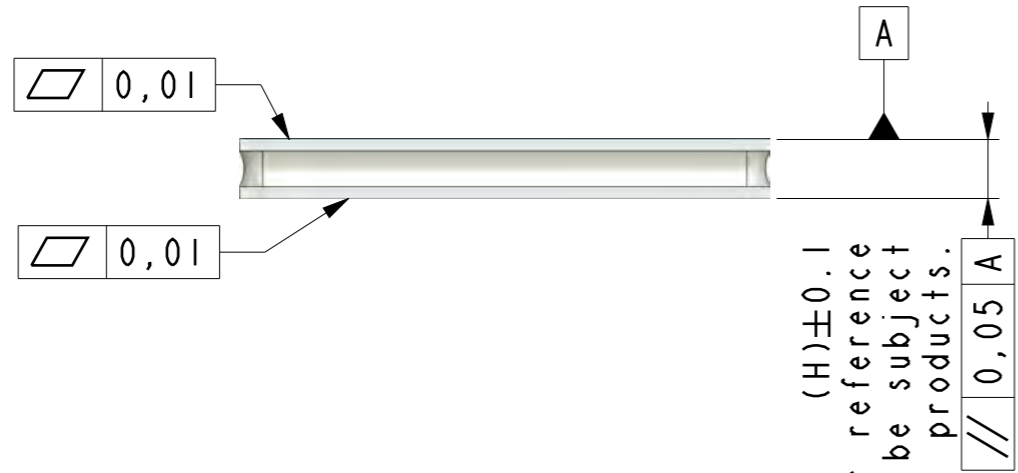
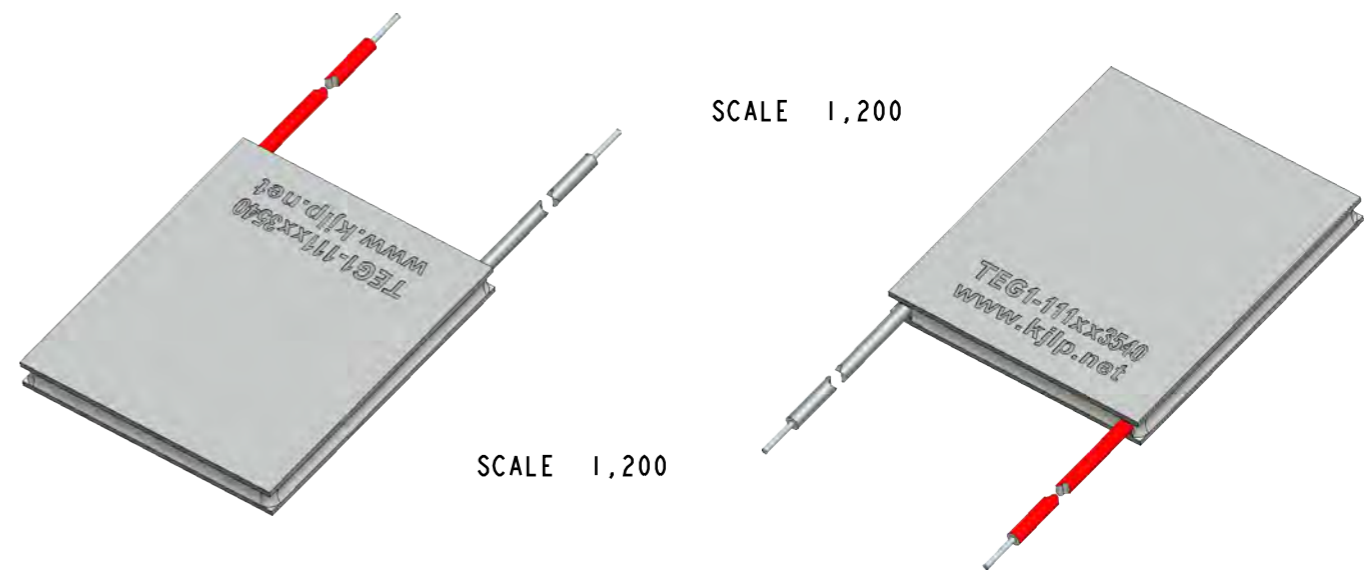


REVISIONS					
REV.	POS.	DESCRIPTION	DATE	DRW	APP
A		INITIAL CREATION	2013/01/01	Gary	Mason



The H is for reference only. Please be subject to the actual products.



Part Number And Feature:

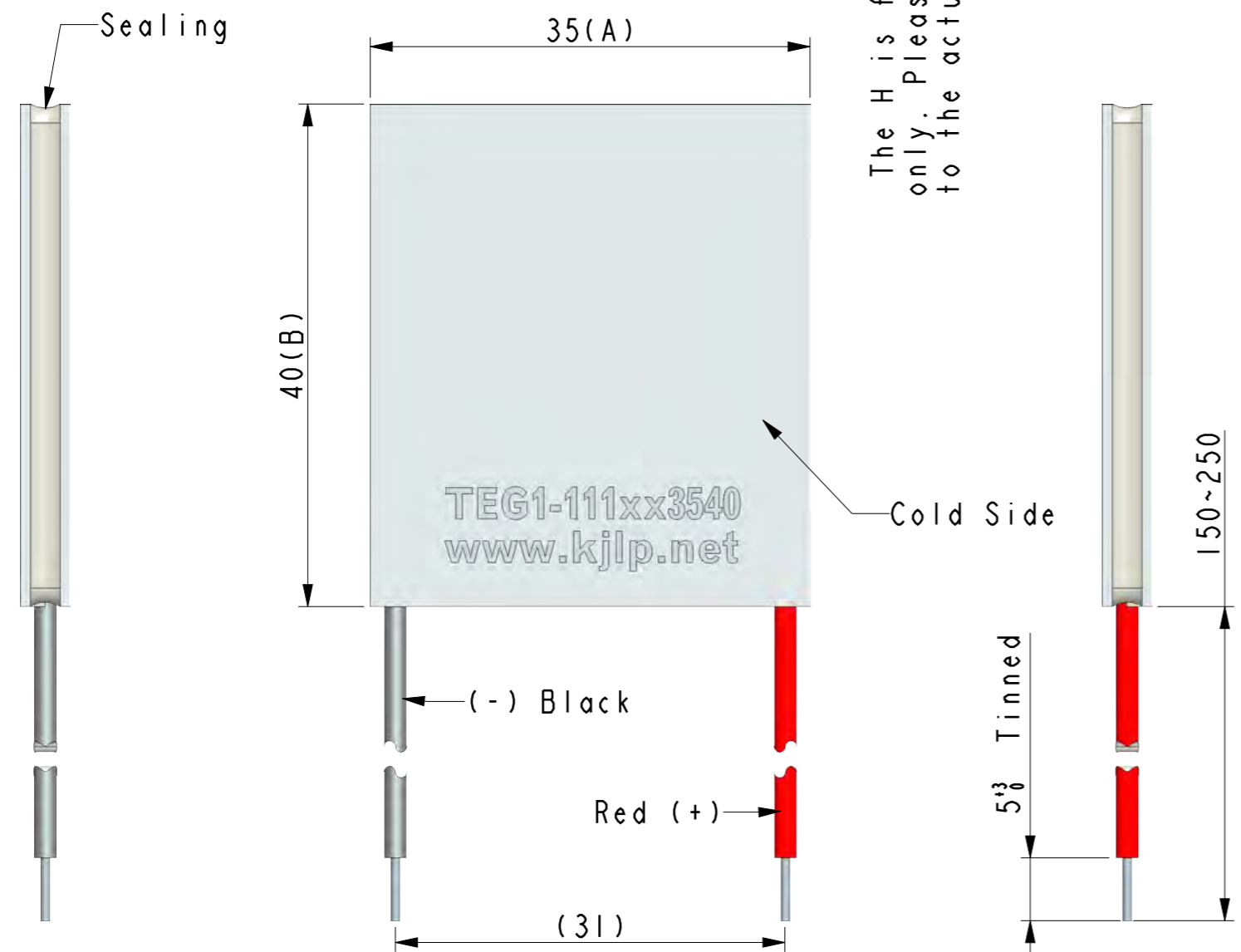
T	E	G	-	I	I	x	x	3	5	4	0	Sealing	YES
Thermo	Electric	Chip	Stage	N & P	Stack	Quantity	R	Load	Dimension (A)	Dimension (B)		Operation Temperatur(Max.)	200°C(Max.)
												Melting Point	235°C
												Storage Temperature	-60°C~100°C
												RoHS	YES

Technical Data:

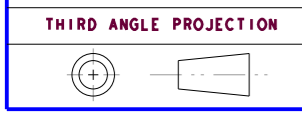
ITEM	Part NO.	Stack(P&N)	U Load(Max.)	P Load(Max.)	R Load(Max.)	Uoc	P/N Size	DIM(A)	DIM(B)	DIM(H)
I	TEGI-111203540	111	3.2 V	5.6 W	2.0 Ohm	6.0 V	1.2*1.4*1.4	35	40	RF3.3

Notes:

1. Printing always on cold side.
2. Torlerance of thermo and electric parameters $\pm 10\%$.
3. Please mount heat sink before you use it. also, please do not exceed the extra voltage at any time.



*DO NOT SCALE DRAWING



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USED OR DISCLOSED OR IN PART TO ANYONE WITHOUT THE PERMISSION OF KJLP (SHENZHEN) ELECTRONICS
CO., LTD.

1. UNLESS OTHERWISE SPECIFIED,
DIMENSIONS ARE MM
2 TOLERANCE ARE AS FOLLOWS:
0 < X < 2 ± 0.06
2 < X < 10 ± 0.08
10 < X < 50 ± 0.12
50 < X < 100 ± 0.16
100 < X < 200 ± 0.20
200 < X < 300 ± 0.30
ANGLES ± 0.5°

PART NO.	TEGI-111xx3540	DESCRIPTION	111 P&N, 5.6W(Max.), 35*40mm		
SIGNATURE		DATE	昆晶冷片(深圳)电子有限公司		
DRAWN BY	Gary	2013/01/01	KJLP (SHENZHEN) ELECTRONICS CO., LTD		
CHECKED BY	Justin	2013/01/01	email: kjlp@kjlp.net http:// www.kjlp.net		
ENGR	Vivi	2013/01/01	Tel: +86-755-82528352 Fax: +86-755-22639899		
APPROVED BY	Mason	2013/01/01	CAD MODLE:	TEGI-111xx3540.prt	SCALE: 1:1 REV: A
MATERIAL:	ISSUED BY	Jack	2013/01/01	CAD DWG:	TEGI-111xx3540.drw
					SIZE: A3 SHEET: 1 OF 1